

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Micron Technology, Inc.	09/26/2008
RECEIVING PARTY DATA	
Name:	Aptina Imaging Corporation
Street Address:	c/o Citco Trustees (Cayman) Ltd.
Internal Address:	Regatta Office Park, West Bay Road
City:	Grand Cayman
State/Country:	CAYMAN ISLANDS
Postal Code:	Y1-1205
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	10845304
CORRESPONDENCE DATA	
Fax Number:	(202)420-2201
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	202-420-2200
Email:	tdamico@dicksteinshapiro.com
Correspondent Name:	Thomas J. D'Amico-DICKSTEIN SHAPIRO LLP
Address Line 1:	1825 Eye Street NW
Address Line 2:	M4065.1296/P1296
Address Line 4:	Washington, DISTRICT OF COLUMBIA 20006-5403
ATTORNEY DOCKET NUMBER:	M4065.1296/P1296
NAME OF SUBMITTER:	Nance S. Pitzer

Total Attachments: 8
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PATENT ASSIGNMENT AGREEMENT

1. Definitions

(a) "Agreement" shall mean this Patent Assignment Agreement.

(b) "Assignee" shall mean **Aptina Imaging Corporation**, a Cayman Islands corporation with offices at c/o Citco Trustees (Cayman) Limited, Regatta Office Park, West Bay Road, Grand Cayman, Y1-1205, Cayman Islands.

(c) "Assignor" shall mean **Micron Technology, Inc.**, a Delaware corporation with offices at 8000 South Federal Way, Boise, ID 83707.

(d) "Effective Date" shall mean October 3, 2008.

(e)



(f)



(g) "Imaging Patents" shall mean those patents identified in ATTACHMENT "A" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(h) "Imaging Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "B" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(i) "Semiconductor Patents" shall mean those patents identified in ATTACHMENT "D" hereto, including, without limitation, all divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts thereof, and which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(j) "Semiconductor Patent Applications" shall mean those filed patent applications identified in ATTACHMENT "E" hereto, including, without limitation, all patents, divisions, continuations, continuations-in-part, reissues, reexaminations, and all foreign counterparts which may issue thereon or in connection therewith after the Effective Date of this Agreement.

(k)

2.

(a) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Imaging Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Imaging Patents to Assignee and to record assignment of the Imaging Patents to Assignee.

(b) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Imaging Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Imaging Patent Applications to Assignee.

(c)

(d) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, and subject further to the restrictions on the Semiconductor Patents set out below, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Semiconductor Patents, including all rights to causes of action and remedies related thereto (including the right to sue for past, present or future infringement of rights related to the foregoing and the right to collect damages therefor). Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to issue the Semiconductor Patents to Assignee and to record assignment of the Semiconductor Patents to Assignee.

(e) Subject to the terms and conditions of this Agreement, and subject to the rights of others existing as of the Effective Date of this Agreement if any, Assignor, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, hereby sells, assigns, and transfers to Assignee its entire right, title and interest in and to the Intellectual Property rights in the Semiconductor Patent Applications. Assignor hereby authorizes and requests the Commissioner of Patents of the United States, and any other official of the United States and any country foreign to the United States whose duty it is to issue or record patents, to record assignment of the Semiconductor Patent Applications to Assignee.

(f)

[REDACTED]

[REDACTED]

[REDACTED]

3 [REDACTED]

[REDACTED]

4. [REDACTED]

[REDACTED]

5. [REDACTED]

[REDACTED]

[REDACTED]

6. [REDACTED]

[REDACTED]

7. General

This Agreement shall be effective as of the Effective Date hereof and shall be binding on the respective heirs, assigns, representatives, and successors of Assignor and of Assignee.

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Agreed to by:

Micron Technology, Inc.

Signed: [Signature]

Date: 9/26/08, 2008

Notarization

State of Idaho
County of Ada

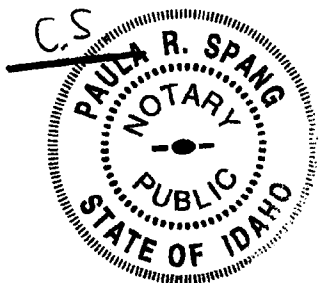
On 9/26/08, before me, Paula R. Spang, personally appeared the above-named Steven R. Appleton

who executed this Assignment in my presence and acknowledged to me that he did so of his own free will and in his authorized capacity for the purposes set forth herein.

Signed: [Signature]

My commission expires: 8/12/11

REVIEWED
MTI LEGAL



Agreed to by:

Aptina Imaging Corporation

Signed: [Signature]

Date: 9/26/08, 2008

Notarization

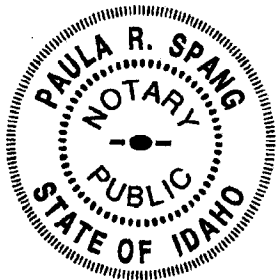
State of Idaho
County of Ada

On 9/26/08, before me, Paula R. Spang, personally appeared the above-named Thomas L. Lewis, Jr.

who executed this Assignment in my presence and acknowledged to me that he did so of his own free will and in his authorized capacity for the purposes set forth herein.

Signed: [Signature]

My commission expires: 8/12/11



[Signature page to the Patent Assignment Agreement]

ATTACHMENT "A"



ATTACHMENT "B"

IMAGING PATENT APPLICATIONS

Aptina Applications

FILE NUMBER	TITLE	STATUS	COUNTRY NAME	APPLICATION NUMBER	DATE FILED
2003-0137.00/JP	COVERS FOR MICROELECTRONIC IMAGERS AND METHODS FOR WAFER-LEVEL PACKAGING OF MICROELECTRONIC IMAGERS	Pending	Japan	2007178513	Apr 27, 2005
2003-0137.00/KR	COVERS FOR MICROELECTRONIC IMAGERS AND METHODS FOR WAFER-LEVEL PACKAGING OF MICROELECTRONIC IMAGERS	Allowed	Republic of Korea	20067026151	Apr 27, 2005
2003-0137.00/PC	COVERS FOR MICROELECTRONIC IMAGERS AND METHODS FOR WAFER-LEVEL PACKAGING OF MICROELECTRONIC IMAGERS	Pending	PCT	PCTUS05014632	Apr 27, 2005
2003-0137.00/SG	COVERS FOR MICROELECTRONIC IMAGERS AND METHODS FOR WAFER-LEVEL PACKAGING OF MICROELECTRONIC IMAGERS	Pending	Singapore	2006077962	Apr 27, 2005
2003-0137.00/US	COVERS FOR MICROELECTRONIC IMAGERS AND METHODS FOR WAFER-LEVEL PACKAGING OF MICROELECTRONIC IMAGERS	Pending	United States of America	10845304	May 13, 2004
2003-0168.01/US	SOI CMOS DEVICE WITH REDUCED DIAPHRAGM	Pending	United States of America	11048035	Jan 28, 2005
2003-0194.00/EP	IMAGE PHOTO DIODE CAPACITOR STRUCTURE WITH REDUCED PROCESS VARIATION SENSITIVITY	Pending	European Patent Office	047573910	Jul 30, 2004
2003-0194.00/JP	IMAGE PHOTO DIODE CAPACITOR STRUCTURE WITH REDUCED PROCESS VARIATION SENSITIVITY	Pending	Japan	2006628522	Jul 30, 2004